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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	48MHz
Connectivity	EBI/EMI, I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	68
Program Memory Size	128KB (64K x 16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	3930 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 15x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-TQFP
Supplier Device Package	80-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f87j11-i-pt

TABLE 1-3: PIC18F6XJ1X PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	64-TQFP			
				PORTF is a bidirectional I/O port.
RF1/AN6/C2OUT	17			
RF1		I/O	ST	Digital I/O.
AN6		I	Analog	Analog Input 6.
C2OUT		O	—	Comparator 2 output.
RF2/PMA5/AN7/C1OUT	16			
RF2		I/O	ST	Digital I/O.
PMA5		O	—	Parallel Master Port address.
AN7		I	Analog	Analog Input 7.
C1OUT		O	—	Comparator 1 output.
RF3/AN8/C2INB	15			
RF3		I/O	ST	Digital input.
AN8		I	Analog	Analog Input 8.
C2INB		I	Analog	Comparator 2 Input B.
RF4/AN9/C2INA	14			
RF4		I/O	ST	Digital input.
AN9		I	Analog	Analog Input 8.
C2INA		I	Analog	Comparator 2 Input A.
RF5/AN10/C1INB/CVREF	13			
RF5		I/O	ST	Digital input.
AN10		I	Analog	Analog Input 10.
C1INB		I	Analog	Comparator 1 Input B.
CVREF		O	Analog	Comparator reference voltage output.
RF6/AN11/C1INA	12			
RF6		I/O	ST	Digital I/O.
AN11		I	Analog	Analog Input 11.
C1INA		I	Analog	Comparator 1 Input A.
RF7/$\overline{SS1}$	11			
RF7		I/O	ST	Digital I/O.
$\overline{SS1}$		I	TTL	SPI slave select input.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; OD = Open-Drain (no P diode to VDD); I^2C = ST with I^2C™ or SMB levels

Note 1: Default assignment for ECCP2/P2A when Configuration bit, CCP2MX, is set.

2: Alternate assignment for ECCP2/P2A when Configuration bit, CCP2MX, is cleared.

FIGURE 5-4: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ NOT TIED TO V_{DD}): CASE 1

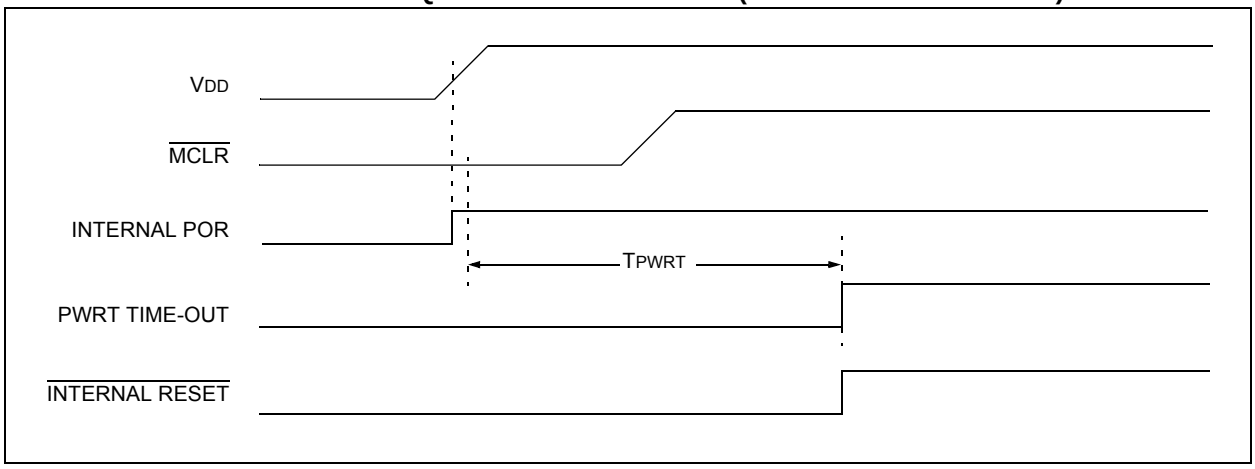


FIGURE 5-5: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ NOT TIED TO V_{DD}): CASE 2

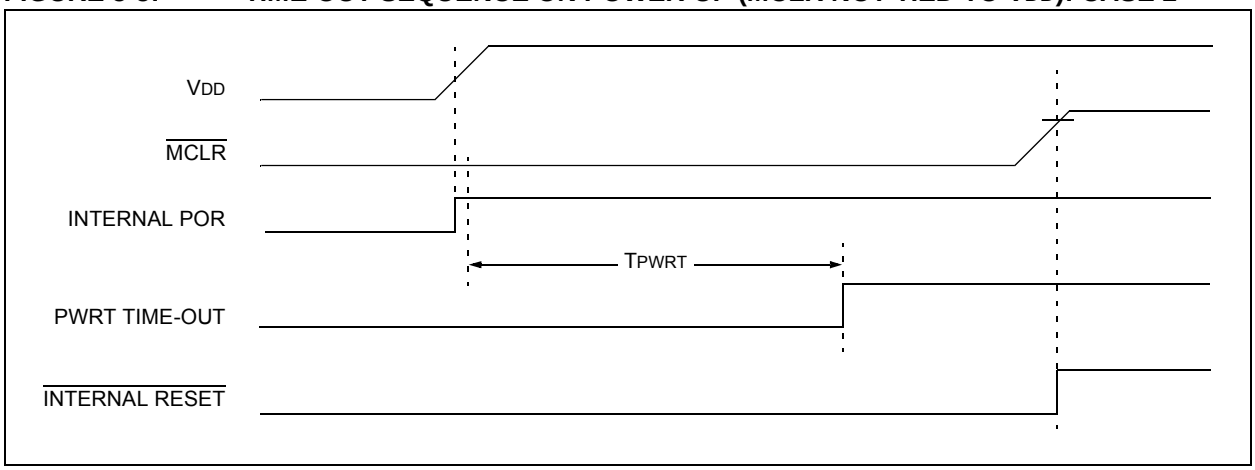


FIGURE 5-6: SLOW RISE TIME ($\overline{MCLR}$ TIED TO V_{DD}, V_{DD} RISE > T_{PWRT})

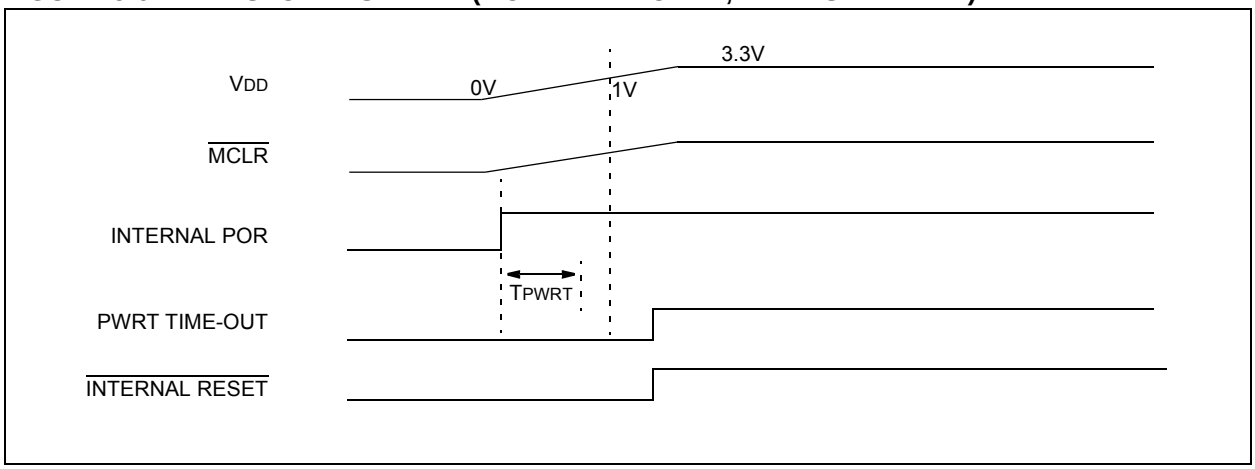


TABLE 5-3: INITIALIZATION CONDITIONS FOR ALL REGISTERS[4] (CONTINUED)

Register	Applicable Devices		Power-on Reset, Brown-out Reset	MCLR Resets, WDT Reset, RESET Instruction, Stack Resets, CM Resets	Wake-up via WDT or Interrupt
ADRESH	PIC18F6XJ1X	PIC18F8XJ1X	xxxx xxxx	uuuu uuuu	uuuu uuuu
ADRESL	PIC18F6XJ1X	PIC18F8XJ1X	xxxx xxxx	uuuu uuuu	uuuu uuuu
ADCON0	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
ADCON1	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
ANCON0	PIC18F6XJ1X	PIC18F8XJ1X	00-0 0000	uu-u uuuu	uu-u uuuu
ANCON1	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	uuuu uuuu	uuuu uuuu
WDTCON	PIC18F6XJ1X	PIC18F8XJ1X	0x-0 ---0	0x-u ---0	ux-u ---u
ECCP1AS	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
ECCP1DEL	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
CCPR1H	PIC18F6XJ1X	PIC18F8XJ1X	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCPR1L	PIC18F6XJ1X	PIC18F8XJ1X	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCP1CON	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
ECCP2AS	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
ECCP2DEL	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
CCPR2H	PIC18F6XJ1X	PIC18F8XJ1X	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCPR2L	PIC18F6XJ1X	PIC18F8XJ1X	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCP2CON	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
ECCP3AS	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
ECCP3DEL	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
CCPR3H	PIC18F6XJ1X	PIC18F8XJ1X	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCPR3L	PIC18F6XJ1X	PIC18F8XJ1X	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCP3CON	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
SPBRG1	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
RCREG1	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
TXREG1	PIC18F6XJ1X	PIC18F8XJ1X	xxxx xxxx	uuuu uuuu	uuuu uuuu
TXSTA1	PIC18F6XJ1X	PIC18F8XJ1X	0000 0010	0000 0010	uuuu uuuu
RCSTA1	PIC18F6XJ1X	PIC18F8XJ1X	0000 000x	0000 000x	uuuu uuuu
SPBRG2	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
RCREG2	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
TXREG2	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
TXSTA2	PIC18F6XJ1X	PIC18F8XJ1X	0000 0010	0000 0010	uuuu uuuu
EECON2	PIC18F6XJ1X	PIC18F8XJ1X	---- ----	---- ----	---- ----
EECON1	PIC18F6XJ1X	PIC18F8XJ1X	--00 x00-	--00 u00-	--00 u00-

Legend: u = unchanged; x = unknown; - = unimplemented bit, read as '0'; q = value depends on condition. Shaded cells indicate conditions do not apply for the designated device.

Note 1: When the wake-up is due to an interrupt and the GIEL or GIEH bit is set, the TOSU, TOSH and TOSL are updated with the current value of the PC. The STKPTR is modified to point to the next location in the hardware stack.

2: When the wake-up is due to an interrupt and the GIEL or GIEH bit is set, the PC is loaded with the interrupt vector (0008h or 0018h).

3: One or more bits in the INTCONx or PIRx registers will be effected (to cause wake-up).

4: See Table 5-2 for Reset value for specific conditions.

TABLE 5-3: INITIALIZATION CONDITIONS FOR ALL REGISTERS(4) (CONTINUED)

Register	Applicable Devices		Power-on Reset, Brown-out Reset	MCLR Resets, WDT Reset, RESET Instruction, Stack Resets, CM Resets	Wake-up via WDT or Interrupt
IPR3	PIC18F6XJ1X	PIC18F8XJ1X	1111 1111	1111 1111	uuuu uuuu
PIR3	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu(3)
PIE3	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
IPR2	PIC18F6XJ1X	PIC18F8XJ1X	111- 1111	111- 1111	uuu- uuuu
PIR2	PIC18F6XJ1X	PIC18F8XJ1X	000- 0000	000- 0000	uuu- uuuu(3)
PIE2	PIC18F6XJ1X	PIC18F8XJ1X	000- 0000	000- 0000	uuu- uuuu
IPR1	PIC18F6XJ1X	PIC18F8XJ1X	1111 1111	1111 1111	uuuu uuuu
PIR1	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu(3)
PIE1	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
RCSTA2	PIC18F6XJ1X	PIC18F8XJ1X	0000 000x	0000 000x	uuuu uuuu
OSCTUNE	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
TRISJ	PIC18F6XJ1X	PIC18F8XJ1X	1111 1111	1111 1111	uuuu uuuu
TRISH	PIC18F6XJ1X	PIC18F8XJ1X	1111 1111	1111 1111	uuuu uuuu
TRISG	PIC18F6XJ1X	PIC18F8XJ1X	---1 1111	---1 1111	---u uuuu
TRISF	PIC18F6XJ1X	PIC18F8XJ1X	1111 111-	1111 111-	uuuu uuu-
TRISE	PIC18F6XJ1X	PIC18F8XJ1X	1111 1111	1111 1111	uuuu uuuu
TRISD	PIC18F6XJ1X	PIC18F8XJ1X	1111 1111	1111 1111	uuuu uuuu
TRISC	PIC18F6XJ1X	PIC18F8XJ1X	1111 1111	1111 1111	uuuu uuuu
TRISB	PIC18F6XJ1X	PIC18F8XJ1X	1111 1111	1111 1111	uuuu uuuu
TRISA	PIC18F6XJ1X	PIC18F8XJ1X	1111 1111	1111 1111	uuuu uuuu
LATJ	PIC18F6XJ1X	PIC18F8XJ1X	xxxx xxxx	uuuu uuuu	uuuu uuuu
LATH	PIC18F6XJ1X	PIC18F8XJ1X	xxxx xxxx	uuuu uuuu	uuuu uuuu
LATG	PIC18F6XJ1X	PIC18F8XJ1X	---x xxxx	---u uuuu	---u uuuu
LATF	PIC18F6XJ1X	PIC18F8XJ1X	xxxx xxx-	uuuu uuu-	uuuu uuu-
LATE	PIC18F6XJ1X	PIC18F8XJ1X	xxxx xxxx	uuuu uuuu	uuuu uuuu
LATD	PIC18F6XJ1X	PIC18F8XJ1X	xxxx xxxx	uuuu uuuu	uuuu uuuu
LATC	PIC18F6XJ1X	PIC18F8XJ1X	xxxx xxxx	uuuu uuuu	uuuu uuuu
LATB	PIC18F6XJ1X	PIC18F8XJ1X	xxxx xxxx	uuuu uuuu	uuuu uuuu
LATA	PIC18F6XJ1X	PIC18F8XJ1X	xxxx xxxx	uuuu uuuu	uuuu uuuu

Legend: u = unchanged; x = unknown; - = unimplemented bit, read as '0'; q = value depends on condition. Shaded cells indicate conditions do not apply for the designated device.

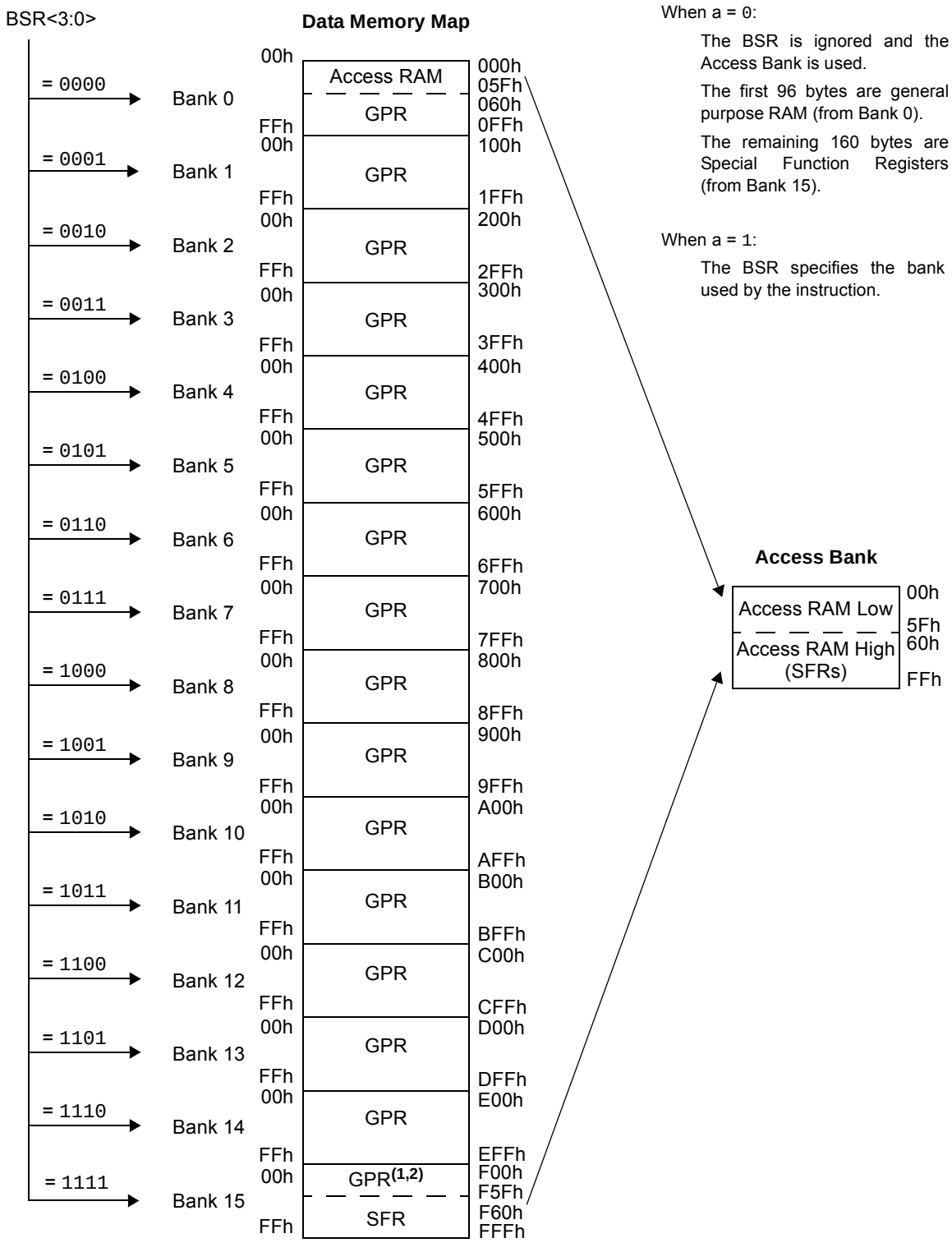
Note 1: When the wake-up is due to an interrupt and the GIEL or GIEH bit is set, the TOSU, TOSH and TOSL are updated with the current value of the PC. The STKPTR is modified to point to the next location in the hardware stack.

2: When the wake-up is due to an interrupt and the GIEL or GIEH bit is set, the PC is loaded with the interrupt vector (0008h or 0018h).

3: One or more bits in the INTCONx or PIRx registers will be effected (to cause wake-up).

4: See Table 5-2 for Reset value for specific conditions.

FIGURE 6-7: DATA MEMORY MAP FOR PIC18F87J11 FAMILY DEVICES



Note 1: Addresses, F5Ah through F5Fh, are also used by SFRs, but are not part of the Access RAM. Users must always use the complete address, or load the proper BSR value, to access these registers.

2: Addresses, F40h to F59h, are not implemented and are not accessible to the user.

7.2.2 TABLE LATCH REGISTER (TABLAT)

The Table Latch (TABLAT) is an 8-bit register mapped into the SFR space. The Table Latch register is used to hold 8-bit data during data transfers between program memory and data RAM.

7.2.3 TABLE POINTER REGISTER (TBLPTR)

The Table Pointer (TBLPTR) register addresses a byte within the program memory. The TBLPTR is comprised of three SFR registers: Table Pointer Upper Byte, Table Pointer High Byte and Table Pointer Low Byte (TBLPTRU:TBLPTRH:TBLPTRL). These three registers join to form a 22-bit wide pointer. The low-order 21 bits allow the device to address up to 2 Mbytes of program memory space. The 22nd bit allows access to the device ID, the user ID and the Configuration bits.

The Table Pointer register, TBLPTR, is used by the TBLRD and TBLWT instructions. These instructions can update the TBLPTR in one of four ways based on the table operation. These operations are shown in Table 7-1. These operations on the TBLPTR only affect the low-order 21 bits.

7.2.4 TABLE POINTER BOUNDARIES

TBLPTR is used in reads, writes and erases of the Flash program memory.

When a TBLRD is executed, all 22 bits of the TBLPTR determine which byte is read from program memory into TABLAT.

When a TBLWT is executed, the seven LSbs of the Table Pointer register (TBLPTR<6:0>) determine which of the 64 program memory holding registers is written to. When the timed write to program memory begins (via the WR bit), the 12 MSbs of the TBLPTR (TBLPTR<21:10>) determine which program memory block of 1024 bytes is written to. For more detail, see **Section 7.5 "Writing to Flash Program Memory"**.

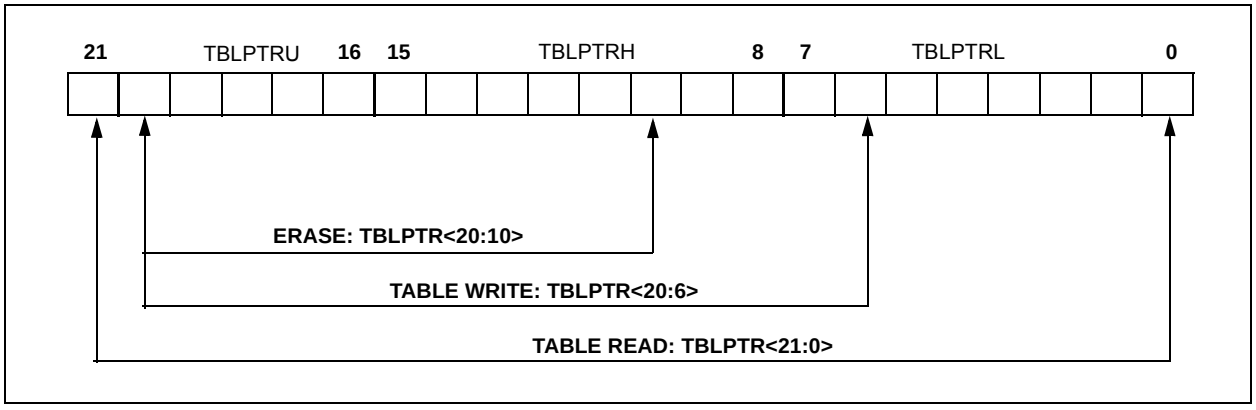
When an erase of program memory is executed, the 12 MSbs of the Table Pointer register point to the 1024-byte block that will be erased. The Least Significant bits are ignored.

Figure 7-3 describes the relevant boundaries of TBLPTR based on Flash program memory operations.

TABLE 7-1: TABLE POINTER OPERATIONS WITH TBLRD AND TBLWT INSTRUCTIONS

Example	Operation on Table Pointer
TBLRD* TBLWT*	TBLPTR is not modified
TBLRD*+ TBLWT*+	TBLPTR is incremented after the read/write
TBLRD*- TBLWT*-	TBLPTR is decremented after the read/write
TBLRD+* TBLWT+*	TBLPTR is incremented before the read/write

FIGURE 7-3: TABLE POINTER BOUNDARIES BASED ON OPERATION



8.6.4 16-BIT MODE TIMING

The presentation of control signals on the External Memory Bus is different for the various operating modes. Typical signal timing diagrams are shown in Figure 8-4 and Figure 8-5.

FIGURE 8-4: EXTERNAL MEMORY BUS TIMING FOR TBLRD (EXTENDED MICROCONTROLLER MODE)

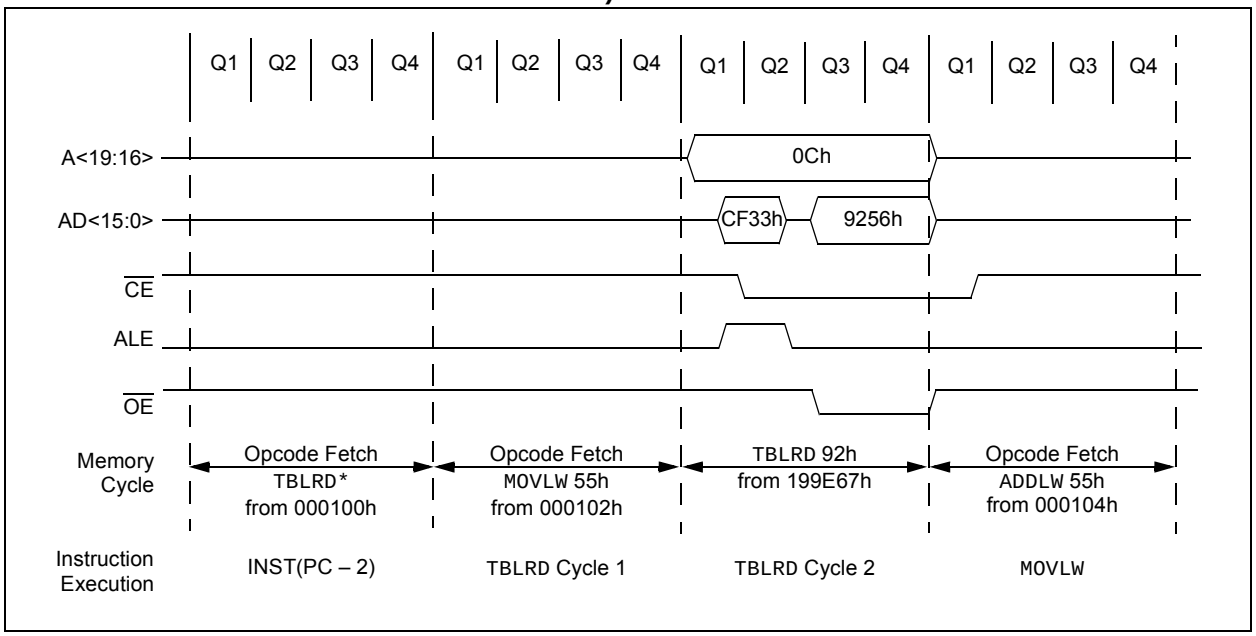


FIGURE 8-5: EXTERNAL MEMORY BUS TIMING FOR SLEEP (EXTENDED MICROCONTROLLER MODE)

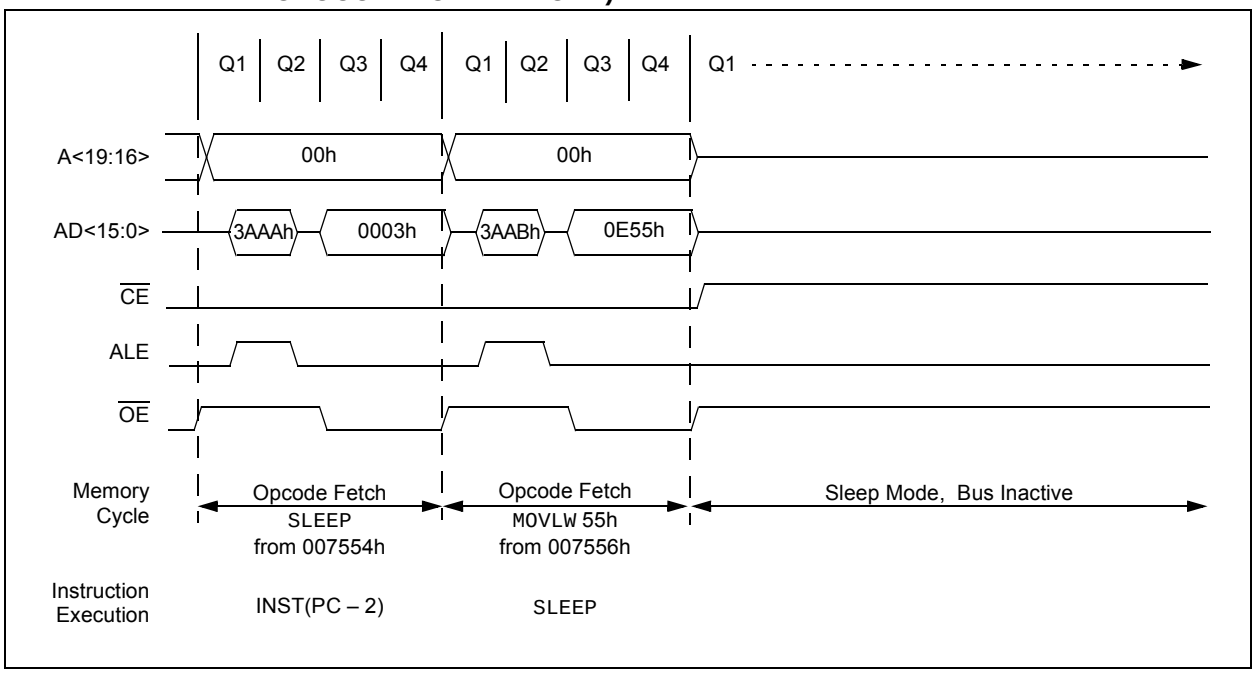


Table 11-2 summarizes the output capabilities of the ports. Refer to the **"Absolute Maximum Ratings"** in **Section 28.0 "Electrical Characteristics"** for more details.

TABLE 11-2: OUTPUT DRIVE LEVELS

Port	Drive	Description
PORTA	Minimum	Intended for indication.
PORTF		
PORTG		
PORTH(1)		
PORTD	Medium	Sufficient drive levels for external memory interfacing as well as indication.
PORTE		
PORTJ(1)		
PORTB	High	Suitable for direct LED drive levels.
PORTC		

Note 1: These ports are not available on 64-pin devices.

11.1.3 PULL-UP CONFIGURATION

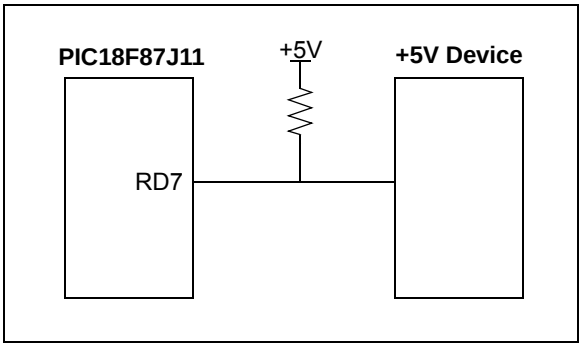
Four of the I/O ports (PORTB, PORTD, PORTE and PORTJ) implement configurable weak pull-ups on all pins. These are internal pull-ups that allow floating digital input signals to be pulled to a consistent level, without the use of external resistors.

The pull-ups are enabled with a single bit for each of the ports: $\overline{\text{RBPU}}$ (INTCON2<7>) for PORTB, and RDPU, REPU and RJPU (PORTG<7:5>) for the other ports.

11.1.4 INTERFACING TO A 5V SYSTEM

Though the V_{DDMAX} of the PIC18F87J11 family is 3.6V, these devices are still capable of interfacing with 5V systems, even if the V_{IH} of the target system is above 3.6V. This is accomplished by adding a pull-up resistor to the port pin (Figure 11-2), clearing the LAT bit for that pin and manipulating the corresponding TRIS bit (Figure 11-1) to either allow the line to be pulled high, or to drive the pin low. Only port pins that are tolerant of voltages up to 5.5V can be used for this type of interface (refer to **Section 11.1.1 "Input Pins and Voltage Considerations"**).

FIGURE 11-2: +5V SYSTEM HARDWARE INTERFACE



EXAMPLE 11-1: COMMUNICATING WITH THE +5V SYSTEM

```
BCF   LATD, 7   ; set up LAT register so
                ; changing TRIS bit will
                ; drive line low
BCF   TRISD, 7  ; send a 0 to the 5V system
BSF   TRISD, 7  ; send a 1 to the 5V system
```

TABLE 11-6: PORTB FUNCTIONS

Pin Name	Function	TRIS Setting	I/O	I/O Type	Description
RB0/INT0/FLT0	RB0	0	O	DIG	LATB<0> data output.
		1	I	TTL	PORTB<0> data input; weak pull-up when $\overline{\text{RBPU}}$ bit is cleared.
	INT0	1	I	ST	External Interrupt 0 input.
	FLT0	1	I	ST	Enhanced PWM Fault input (ECCP1 module); enabled in software.
RB1/INT1/ PMA4	RB1	0	O	DIG	LATB<1> data output.
		1	I	TTL	PORTB<1> data input; weak pull-up when $\overline{\text{RBPU}}$ bit is cleared.
	INT1	1	I	ST	External Interrupt 1 input.
	PMA4	x	O	—	Parallel Master Port address out.
RB2/INT2/ PMA3	RB2	0	O	DIG	LATB<2> data output.
		1	I	TTL	PORTB<2> data input; weak pull-up when $\overline{\text{RBPU}}$ bit is cleared.
	INT2	1	I	ST	External Interrupt 2 input.
	PMA3	x	O	—	Parallel Master Port address out.
RB3/INT3/ PMA2/ECCP2/ P2A	RB3	0	O	DIG	LATB<3> data output.
		1	I	TTL	PORTB<3> data input; weak pull-up when $\overline{\text{RBPU}}$ bit is cleared.
	INT3	1	I	ST	External Interrupt 3 input.
	PMA2	x	O	—	Parallel Master Port address out.
	ECCP2(1)	0	O	DIG	ECCP2 compare output and CCP2 PWM output; takes priority over port data.
		1	I	ST	ECCP2 capture input.
	P2A(1)	0	O	DIG	ECCP2 Enhanced PWM output, Channel A. May be configured for tri-state during Enhanced PWM shutdown events. Takes priority over port data.
RB4/KBI0/ PMA1	RB4	0	O	DIG	LATB<4> data output.
		1	I	TTL	PORTB<4> data input; weak pull-up when $\overline{\text{RBPU}}$ bit is cleared.
	KBI0		I	TTL	Interrupt-on-pin change.
	PMA1	x	O	—	Parallel Master Port address out.
RB5/KBI1/ PMA0	RB5	0	O	DIG	LATB<5> data output.
		1	I	TTL	PORTB<5> data input; weak pull-up when $\overline{\text{RBPU}}$ bit is cleared.
	KBI1		I	TTL	Interrupt-on-pin change.
	PMA0	x	O	—	Parallel Master Port address out.
RB6/KBI2/PGC	RB6	0	O	DIG	LATB<6> data output.
		1	I	TTL	PORTB<6> data input; weak pull-up when $\overline{\text{RBPU}}$ bit is cleared.
	KBI2	1	I	TTL	Interrupt-on-pin change.
	PGC	x	I	ST	Serial execution (ICSP™) clock input for ICSP and ICD operation.(2)
RB7/KBI3/PGD	RB7	0	O	DIG	LATB<7> data output.
		1	I	TTL	PORTB<7> data input; weak pull-up when $\overline{\text{RBPU}}$ bit is cleared.
	KBI3	1	I	TTL	Interrupt-on-pin change.
	PGD	x	O	DIG	Serial execution data output for ICSP and ICD operation.(2)
		x	I	ST	Serial execution data input for ICSP and ICD operation.(2)

Legend: O = Output, I = Input, DIG = Digital Output, ST = Schmitt Buffer Input, TTL = TTL Buffer Input, x = Don't care (TRIS bit does not affect port direction or is overridden for this option).

Note 1: Alternate assignment for ECCP2/P2A when the CCP2MX Configuration bit is cleared (Extended Microcontroller mode, 80-pin devices only); the default assignment is RC1.

2: All other pin functions are disabled when ICSP™ or ICD is enabled.

TABLE 11-20: PORTJ FUNCTIONS

Pin Name	Function	TRIS Setting	I/O	I/O Type	Description
RJ0/ALE	RJ0	0	O	DIG	LATJ<0> data output.
		1	I	ST	PORTJ<0> data input.
	ALE	x	O	DIG	External Memory Interface address latch enable control output; takes priority over digital I/O.
RJ1/$\overline{OE}$	RJ1	0	O	DIG	LATJ<1> data output.
		1	I	ST	PORTJ<1> data input.
	$\overline{OE}$	x	O	DIG	External Memory Interface output enable control output; takes priority over digital I/O.
RJ2/$\overline{WRL}$	RJ2	0	O	DIG	LATJ<2> data output.
		1	I	ST	PORTJ<2> data input.
	$\overline{WRL}$	x	O	DIG	External Memory Bus write low byte control; takes priority over digital I/O.
RJ3/$\overline{WRH}$	RJ3	0	O	DIG	LATJ<3> data output.
		1	I	ST	PORTJ<3> data input.
	$\overline{WRH}$	x	O	DIG	External Memory Interface write high byte control output; takes priority over digital I/O.
RJ4/BA0	RJ4	0	O	DIG	LATJ<4> data output.
		1	I	ST	PORTJ<4> data input.
	BA0	x	O	DIG	External Memory Interface Byte Address 0 control output; takes priority over digital I/O.
RJ5/$\overline{CE}$	RJ5	0	O	DIG	LATJ<5> data output.
		1	I	ST	PORTJ<5> data input.
	$\overline{CE}$	x	O	DIG	External Memory Interface chip enable control output; takes priority over digital I/O.
RJ6/$\overline{LB}$	RJ6	0	O	DIG	LATJ<6> data output.
		1	I	ST	PORTJ<6> data input.
	$\overline{LB}$	x	O	DIG	External Memory Interface lower byte enable control output; takes priority over digital I/O.
RJ7/$\overline{UB}$	RJ7	0	O	DIG	LATJ<7> data output.
		1	I	ST	PORTJ<7> data input.
	$\overline{UB}$	x	O	DIG	External Memory Interface upper byte enable control output; takes priority over digital I/O.

Legend: O = Output, I = Input, DIG = Digital Output, ST = Schmitt Buffer Input,
x = Don't care (TRIS bit does not affect port direction or is overridden for this option).

TABLE 11-21: SUMMARY OF REGISTERS ASSOCIATED WITH PORTJ

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page:
PORTJ(1)	RJ7	RJ6	RJ5	RJ4	RJ3	RJ2	RJ1	RJ0	65
LATJ(1)	LATJ7	LATJ6	LATJ5	LATJ4	LATJ3	LATJ2	LATJ1	LATJ0	64
TRISJ(1)	TRISJ7	TRISJ6	TRISJ5	TRISJ4	TRISJ3	TRISJ2	TRISJ1	TRISJ0	64
PORTG	RDPU	REPU	RJPU(1)	RG4	RG3	RG2	RG1	RG0	65

Legend: Shaded cells are not used by PORTJ.

Note 1: Unimplemented on 64-pin devices, read as '0'.

FIGURE 12-23: READ TIMING, 16-BIT MULTIPLEXED DATA, PARTIALLY MULTIPLEXED ADDRESS

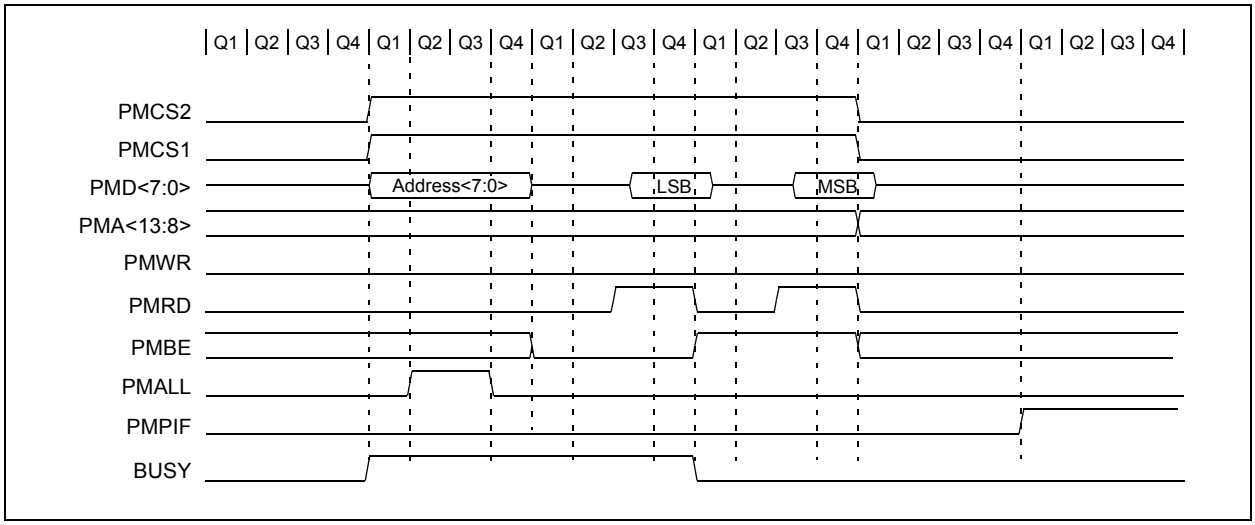
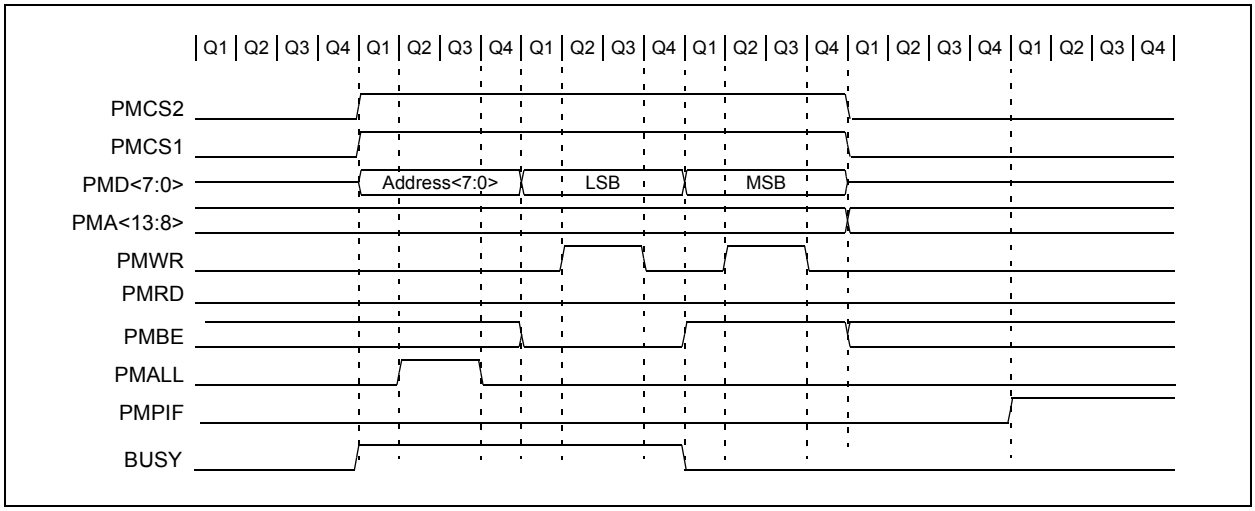


FIGURE 12-24: WRITE TIMING, 16-BIT MULTIPLEXED DATA, PARTIALLY MULTIPLEXED ADDRESS



20.3.6 MASTER MODE

The master can initiate the data transfer at any time because it controls the SCKx. The master determines when the slave (Processor 1, Figure 20-2) is to broadcast data by the software protocol.

In Master mode, the data is transmitted/received as soon as the SSPxBUF register is written to. If the SPI is only going to receive, the SDOx output could be disabled (programmed as an input). The SSPxSR register will continue to shift in the signal present on the SDIx pin at the programmed clock rate. As each byte is received, it will be loaded into the SSPxBUF register as if a normal received byte (interrupts and status bits appropriately set). This could be useful in receiver applications as a “Line Activity Monitor” mode.

The clock polarity is selected by appropriately programming the CKP bit (SSPxCON1<4>). This then, would give waveforms for SPI communication as shown in Figure 20-3, Figure 20-5 and Figure 20-6, where the MSB is transmitted first. In Master mode, the SPI clock rate (bit rate) is user programmable to be one of the following:

- FOSC/4 (or TCY)
- FOSC/16 (or 4 • TCY)
- FOSC/64 (or 16 • TCY)
- Timer2 output/2

This allows a maximum data rate (at 40 MHz) of 10.00 Mbps.

Figure 20-3 shows the waveforms for Master mode. When the CKE bit is set, the SDOx data is valid before there is a clock edge on SCKx. The change of the input sample is shown based on the state of the SMP bit. The time when the SSPxBUF is loaded with the received data is shown.

FIGURE 20-3: SPI MODE WAVEFORM (MASTER MODE)

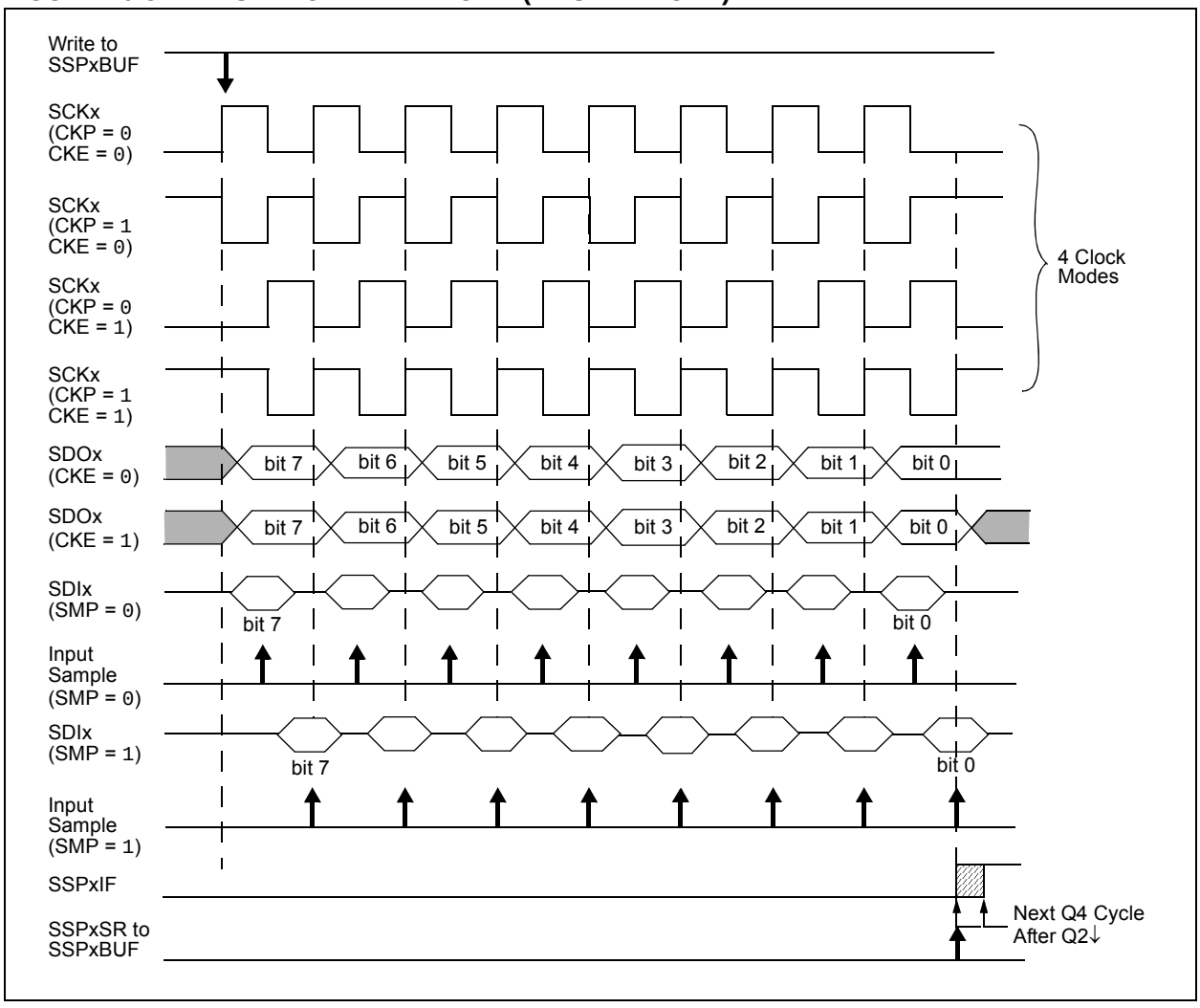
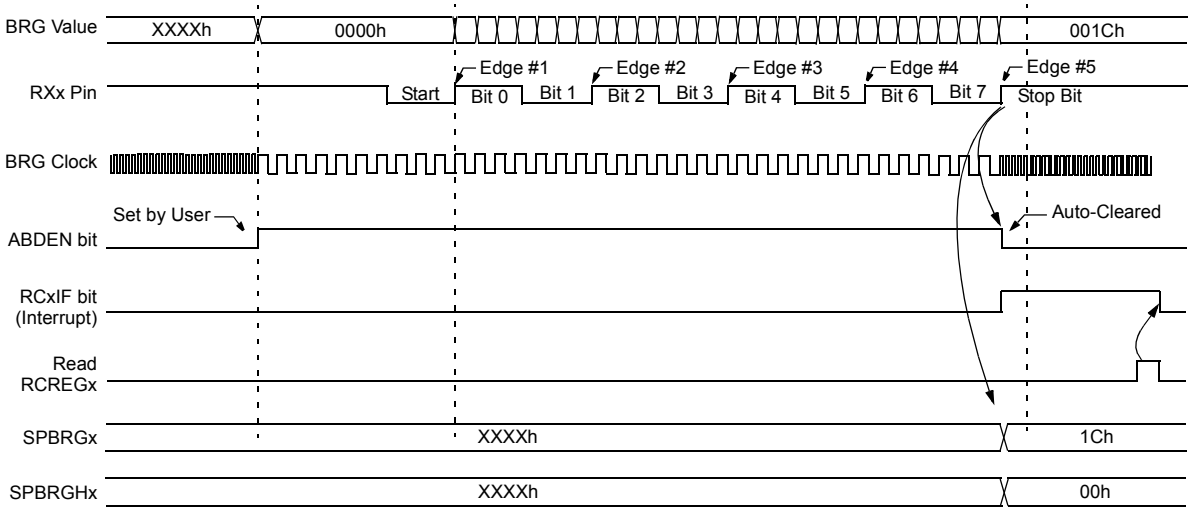
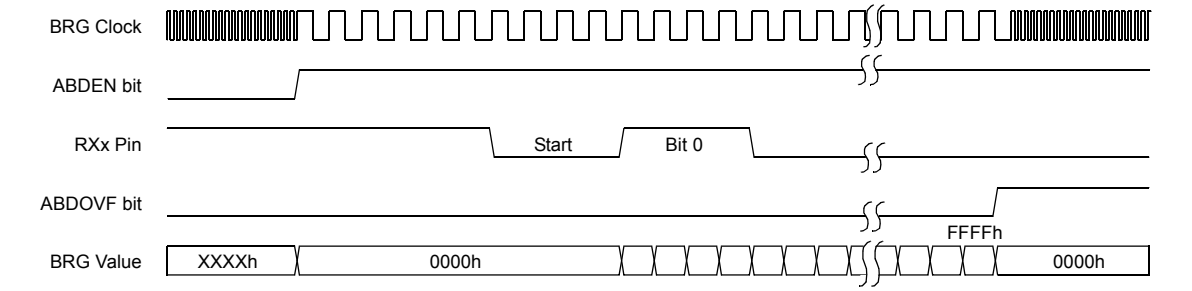


FIGURE 21-1: AUTOMATIC BAUD RATE CALCULATION



Note: The ABD sequence requires the EUSARTx module to be configured in Asynchronous mode and WUE = 0.

FIGURE 21-2: BRG OVERFLOW SEQUENCE



REGISTER 25-7: DEVID1: DEVICE ID REGISTER 1 FOR PIC18F87J11 FAMILY DEVICES

R	R	R	R	R	R	R	R
DEV2	DEV1	DEV0	REV4	REV3	REV2	REV1	REV0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-5 **DEV<2:0>:** Device ID bits
See Register 25-8 for a complete listing.

bit 4-0 **REV<4:0>:** Revision ID bits
These bits are used to indicate the device revision.

REGISTER 25-8: DEVID2: DEVICE ID REGISTER 2 FOR PIC18F87J11 FAMILY DEVICES

R	R	R	R	R	R	R	R
DEV10	DEV9	DEV8	DEV7	DEV6	DEV5	DEV4	DEV3
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 **DEV<10:3>:** Device ID bits:

DEV<10:3> (DEVID2<7:0>)	DEV<2:0> (DEVID1<7:5>)	Device
0100 0100	010	PIC18F66J11
0100 0100	011	PIC18F66J16
0100 0100	100	PIC18F67J11
0100 0100	111	PIC18F86J11
0100 0101	000	PIC18F86J16
0100 0101	001	PIC18F87J11

REGISTER 25-9: WDTCON: WATCHDOG TIMER CONTROL REGISTER

R/W-0	R-x	U-0	R/W-0	U-0	U-0	U-0	U-0
REGSLP	LVDSTAT	—	ADSHR	—	—	—	SWDTEN(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **REGSLP:** Voltage Regulator Low-Power Operation Enable bit
1 = On-chip regulator enters low-power operation when device enters Sleep mode
0 = On-chip regulator is active, even in Sleep mode

bit 6 **LVDSTAT:** LVD Status bit
1 = V_{DDCORE} > 2.45V
0 = V_{DDCORE} < 2.45V

bit 5 **Unimplemented**: Read as '0'

bit 4 **ADSHR:** Shared Address SFR Select bit
For details of bit operation, see Register 6-3.

bit 3-1 **Unimplemented**: Read as '0'

bit 0 **SWDTEN:** Software Controlled Watchdog Timer Enable bit(1)
1 = Watchdog Timer is on
0 = Watchdog Timer is off

Note 1: This bit has no effect if the Configuration bit, WDTEN, is enabled.

TABLE 25-3: SUMMARY OF WATCHDOG TIMER REGISTERS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page:
RCON	IPEN	—	$\overline{CM}$	$\overline{RI}$	$\overline{TO}$	$\overline{PD}$	$\overline{POR}$	$\overline{BOR}$	62
WDTCON	REGSLP	LVDSTAT	—	ADSHR	—	—	—	SWDTEN	63

Legend: — = unimplemented, read as '0'. Shaded cells are not used by the Watchdog Timer.

RETURN **Return from Subroutine**

Syntax: RETURN {s}

Operands: s ∈ [0,1]

Operation: (TOS) → PC;
if s = 1,
(WS) → W,
(STATUSS) → STATUS,
(BSRS) → BSR,
PCLATU, PCLATH are unchanged

Status Affected: None

Encoding:

0000	0000	0001	001s

Description: Return from subroutine. The stack is popped and the top of the stack (TOS) is loaded into the Program Counter. If 's'= 1, the contents of the shadow registers WS, STATUSS and BSRS are loaded into their corresponding registers W, STATUS and BSR. If 's' = 0, no update of these registers occurs.

Words: 1

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No operation	Process Data	POP PC from stack
No operation	No operation	No operation	No operation

Example: RETURN

After Instruction:
PC = TOS

RLCF **Rotate Left f through Carry**

Syntax: RLCF f {,d {,a}}

Operands: 0 ≤ f ≤ 255
d ∈ [0,1]
a ∈ [0,1]

Operation: (f<n>) → dest<n + 1>,
(f<7>) → C,
(C) → dest<0>

Status Affected: C, N, Z

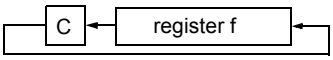
Encoding:

0011	01da	ffff	ffff

Description: The contents of register 'f' are rotated one bit to the left through the Carry flag. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is stored back in register 'f'.

If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.

If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 26.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.



Words: 1

Cycles: 1

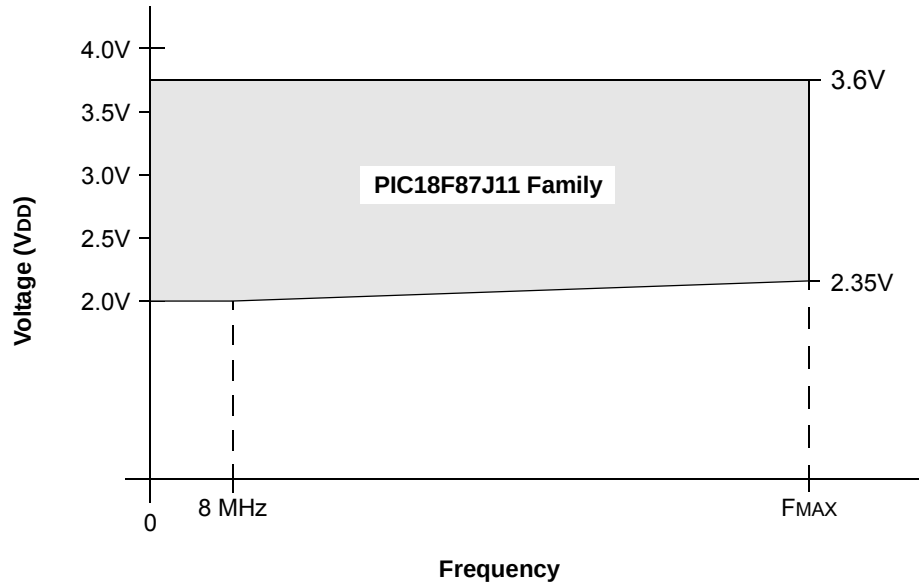
Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: RLCF REG, 0, 0

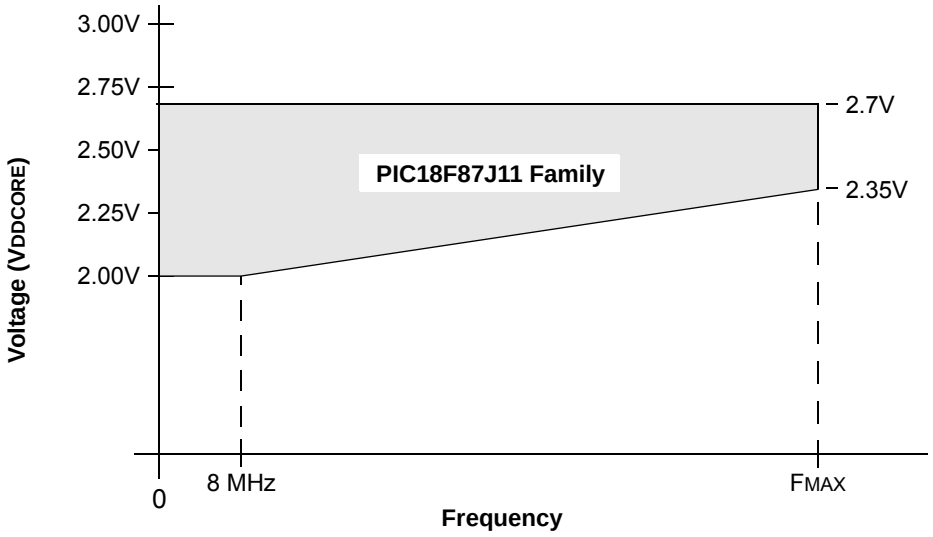
Before Instruction
REG = 1110 0110
C = 0
After Instruction
REG = 1110 0110
W = 1100 1100
C = 1

FIGURE 28-1: PIC18F87J11 FAMILY VOLTAGE-FREQUENCY GRAPH, REGULATOR ENABLED (INDUSTRIAL)



FMAX = 25 MHz in 8-Bit External Memory mode
FMAX = 48 MHz in all other modes

FIGURE 28-2: PIC18F87J11 FAMILY VOLTAGE-FREQUENCY GRAPH, REGULATOR DISABLED (INDUSTRIAL)(0)



FMAX = 25 MHz in 8-Bit External Memory mode
FMAX = 48 MHz in all other modes

Note 1: When the on-chip voltage regulator is disabled, VDD and VDDCORE must be maintained so that VDDCORE ≤ VDD ≤ 3.6V.

28.2 DC Characteristics: Power-Down and Supply Current PIC18F87J11 Family (Industrial) (Continued)

PIC18F87J11 Family (Industrial)		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**		
	Supply Current (IDD) Cont.(2,3)						
	All devices	0.17	0.35	mA	-40°C	VDD = 2.0V, VDDCORE = 2.0V(4)	FOSC = 1 MHz (**PRI_RUN** mode, EC oscillator)
		0.18	0.35	mA	+25°C		
		0.20	0.42	mA	+85°C		
	All devices	0.29	0.52	mA	-40°C	VDD = 2.5V, VDDCORE = 2.5V(4)	
		0.31	0.52	mA	+25°C		
		0.34	0.61	mA	+85°C		
	All devices	0.59	1.1	mA	-40°C	VDD = 3.3V(5)	
		0.44	0.85	mA	+25°C		
		0.42	0.85	mA	+85°C		
	All devices	0.70	1.25	mA	-40°C	VDD = 2.0V, VDDCORE = 2.0V(4)	FOSC = 4 MHz (**PRI_RUN** mode, EC oscillator)
		0.75	1.25	mA	+25°C		
		0.79	1.36	mA	+85°C		
	All devices	1.10	1.7	mA	-40°C	VDD = 2.5V, VDDCORE = 2.5V(4)	
		1.10	1.7	mA	+25°C		
		1.12	1.82	mA	+85°C		
	All devices	1.55	1.95	mA	-40°C	VDD = 3.3V(5)	
		1.47	1.89	mA	+25°C		
		1.54	1.92	mA	+85°C		
	All devices	9.9	14.8	mA	-40°C	VDD = 2.5V, VDDCORE = 2.5V(4)	FOSC = 48 MHz (**PRI_RUN** mode, EC oscillator)
		9.5	14.8	mA	+25°C		
		10.1	15.2	mA	+85°C		
	All devices	13.3	23.2	mA	-40°C	VDD = 3.3V(5)	
		12.2	22.7	mA	+25°C		
		12.1	22.7	mA	+85°C		

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in a high-impedance state and tied to VDD or VSS, and all features that add delta current are disabled (such as WDT, Timer1 oscillator, BOR, etc.).

2: The supply current is mainly a function of the operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD;
MCLR = VDD; WDT is enabled/disabled as specified.

3: Standard, low-cost 32 kHz crystals have an operating temperature range of -10°C to +70°C. Extended temperature crystals are available at a much higher cost.

4: Voltage regulator is disabled (ENVREG = 0, tied to VSS).

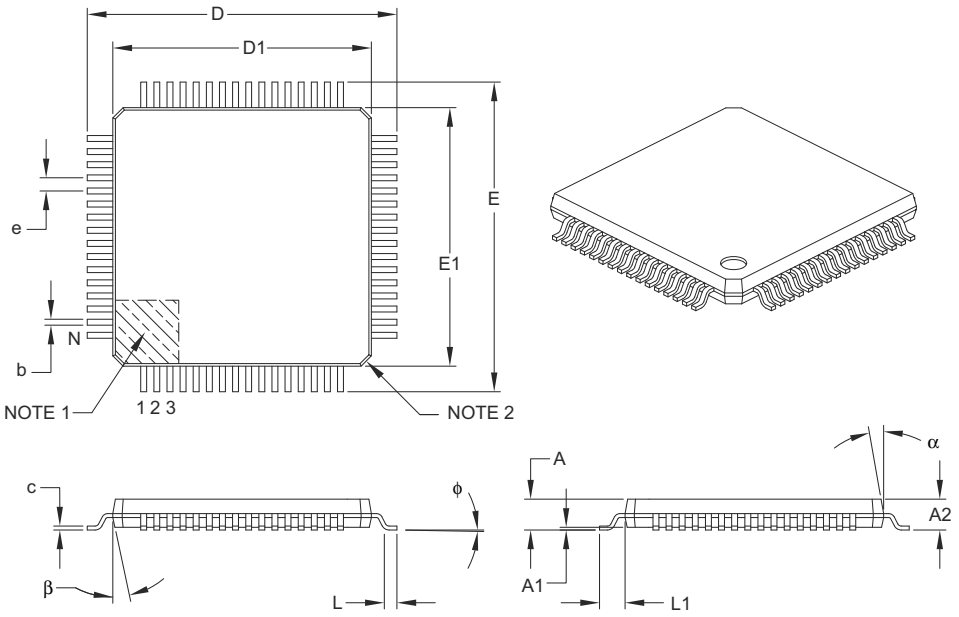
5: Voltage regulator is enabled (ENVREG = 1, tied to VDD, REGSLP = 1).

29.2 Package Details

The following sections give the technical details of the packages.

64-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		64	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-085B

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

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